

Zero support Mass Detectors (ZMD)

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Science and Technology Facilities Council



Work Funded by STFC, QMUL and Micron Semiconductor Ltd..



Q1) What happens if we take thin film of silicon, stress it and use the strength of the material as mechanical support?

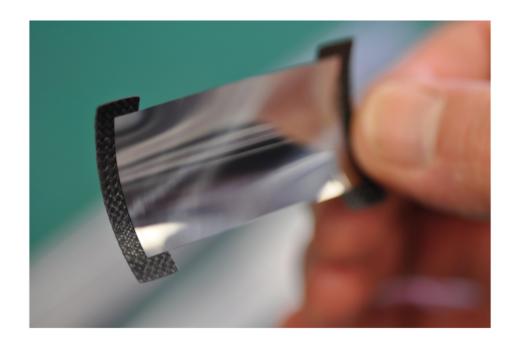
Q2) What then happens if we try and use the silicon as a radiation detector.

e.g. can we build a new type of low mass cylindrical silicon tracker, that could be of interest to industry as well as STFC science.

Start of a cross-disciplinary collaboration between condensed matter and particle physicists.



Constructed some mechanical mock ups to put to one side for a few years to see if they remained stable or not.



CRFP support at each end sufficient to make a rigid structure.

STFC infrastructure for the LHC programme used to measure the shape of the surface of these kinds of bent silicon prototypes.

7 years later this model is still intact.

Start of a cross-disciplinary collaboration between condensed matter and particle physicists.

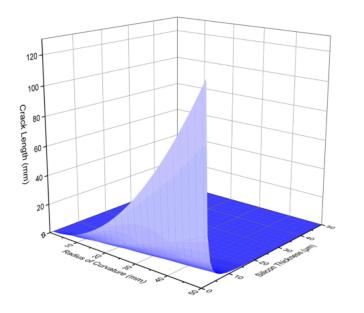


- •IAA funding (20k) used to start work with Micron Semiconductor Ltd.
- •Leveraged 100k of in-kind support from Micron.
- •Using TTT10 (10x10cm strip detector designed by Caltech for a space application).
- 50µm thick silicon sensors
- Need testing
- Need to be assembled into modules for further evaluation.





- Investigation into spherical deformation of thin silicon: undergraduate group project: adapt silicon shape to match focal plane of optical systems (e.g. cameras and telescopes).
- Demonstrated spherical curvature suitable for telescope design.



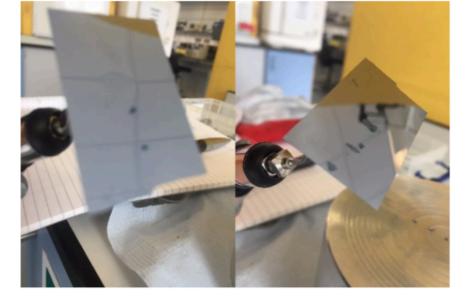
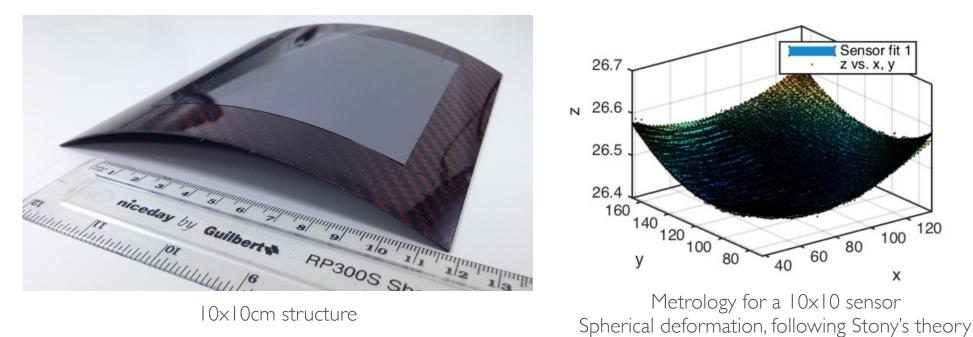


Figure 3: The relationship between the Crack length vs Radius of curvature vs Silicon thickness.



- Undergraduate project student systematically worked through making prototype modules.
- •Allowed us to evolve vacuum jig technology for assembly.

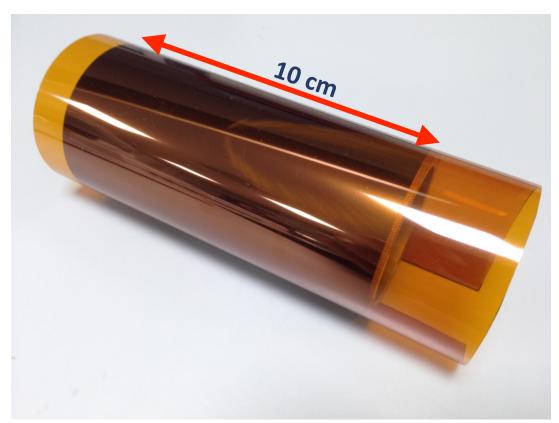




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Cylindrical deformation of a 10x10cm ultra-thin silicon sample also demonstrated.

R = 2.5cm





- •Opportunities Call funding: ~178k over 18 months to build and characterise modules.
 - •Funding to develop and evaluate a proof of concept for low mass tracking and future product design.
 - Data generated from a R=15cm model will allow us to target product design with MSL for cylindrical wrap-around detectors.
 - PDRA starts 1st Feb 2021.
- •Will open the door for us to work with Specialised Imaging on spherically deformed sensors (more challenging: the Kirana CMOS MAPS sensor designed by RAL-TD), and to work with RAL PPD on developing future tracker technologies based on their CMOS chips.